

Title (en)

METHOD FOR PRODUCING METALLIC MICROSTRUCTURES AND USE OF THIS METHOD IN THE PRODUCTION OF SENSOR DEVICES FOR DETECTING FINGERPRINTS

Title (de)

VERFAHREN ZUR HERSTELLUNG METALLISCHER FEINSTRUKTUREN UND ANWENDUNG DES VERFAHRENS BEI DER HERSTELLUNG VON SENSORANORDNUNGEN ZUR ERFASSUNG VON FINGERABDRÜCKEN

Title (fr)

PROCEDE POUR PRODUIRE DES STRUCTURES FINES METALLIQUES ET MISE EN OEUVRE DUDIT PROCEDE LORS DE LA PRODUCTION DE DISPOSITIFS DETECTEURS SERVANT A DETECTER DES EMPREINTES DIGITALES

Publication

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Application

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Priority

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Abstract (en)

[origin: WO0013130A2] First strip conductors (5), a first insulating layer (6), fine structures with first electrodes (51), two strip conductors (7), second electrodes (71) and finally a second insulating layer (8) are deposited one after the other on a base layer (3) that is preferably flexible. The first electrodes (51) are connected to the assigned strip conductors (5) by means of throughplatings. Changes caused by the cuticular sulci of a finger pad in the stray capacitance between adjacent first and second electrodes are evaluated to detect fingerprints.

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G06K 9/00

IPC 8 full level

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